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**Announcement of the
62nd Annual**



June 21-23, 2004

CALL FOR PAPERS

Abstract Deadline: March 2, 2004
Late News Deadline: May 30, 2004



www.tms.org/Meetings/Specialty/DRC/2004/DRC-2004-Home.html



The DRC brings together scientists, engineers, and students to present breakthroughs and advances in device research. DRC is sponsored by the IEEE, Electron Devices Society. The conference will be held at the University of Notre Dame, Notre Dame, Indiana from Monday, June 21 through Wednesday, June 23, 2004.

The DRC will be coordinated with the EMC (Electronic Materials Conference) during the same week, June 23-25, 2004, at the University of Notre Dame. The coordinated efforts are made in recognition of the strong interaction between device and electronic materials research and provides for fruitful exchange of information between attendees of both conferences. For further information about the EMC, see www.tms.org/Meetings/Specialty/EMC04/EMC04.html.

PLENARY AND INVITED SPEAKERS

Plenary and invited speakers will present the latest developments in emerging device technologies including scaled silicon, wide bandgaps, carbon nanotubes, molecular electronics, large-area electronics, bio-inspired electronics, and spintronics.

Partial List of Invited Speakers:

- Yasuhiko Arakawa (University of Tokyo)
- Sanjay Banerjee (University of Texas, Austin)
- David Emerson (CREE, Inc.)
- Stephen Emedocles (Nanosys, Inc.)
- Mark Hershman (Northwestern University)
- Thomas Jackson (Penn State University)
- Thomas Knight (Massachusetts Institute of Technology)
- Mark Lundstrom (Purdue University)
- Richard Martel (University of Montreal)
- Umesh Mishra (University of California, Santa Barbara)
- Hiroo Munekata (Tokyo Institute of Technology)
- Nongjian Tao (Arizona State University)
- Lukas Worschech (University of Wurzburg)

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Yifeng Wu, CREE Santa Barbara Technology Center

John Zolper, DARPA/MTO

POSTER AND RUMP SESSIONS

Building on the success of poster sessions in previous years, abstracts will again be accepted for poster presentations at DRC 2004. In the DRC tradition, rump sessions will continue to provide a forum for frank discussion of contentious topics in device research and applications.

BEST STUDENT PAPER AWARD

Papers presented by students, based on their own research, are eligible for this annual award. The abstract must be identified as a "Student Paper" during the submission process to be eligible for this award.

CALL FOR PAPERS

Authors are requested to see the DRC website, www.tms.org/Meetings/Specialty/DRC/2004/DRC-2004-Home.html for paper submission instructions, or contact Alan Seabaugh, Technical Program Chair. Abstracts sent by facsimile will not be accepted.

Abstracts submitted to DRC may not be submitted to EMC.

ABSTRACT DEADLINE: March 2, 2004

FURTHER INFORMATION

Note: Registration and Housing information will be available in April 2004.

Early registration is encouraged with a reduced registration fee offered as an incentive. Students will also receive a reduced registration fee. Limited travel funds are available to students presenting papers. Further information on student assistance may be obtained by writing to Pallab Bhat-tacharya, General Program Chair.

PAPERS ARE SOLICITED ON HIGH PERFORMANCE AND NOVEL DEVICES INCLUDING, BUT NOT LIMITED TO THE FOLLOWING:

- Amorphous & polycrystalline devices
- Carbon nanotube devices
- Devices for displays & imaging
- Device modeling
- III-V FET and bipolar transistors
- Integrated optoelectronics
- High voltage/high power devices
- Magnetic devices
- Micro/nanoelectromechanical devices
- Millimeter wave and ultrafast devices
- Molecular devices
- Nanofabrication technology for devices
- Nonvolatile, static and dynamic memory
- Optical sources and detectors
- Organic emitters and transistors
- Plastic electronics
- Quantum-effect and single-electron devices
- Reliability
- Sensors
- SiGe, SiGeC, and SiC devices
- Silicon CMOS/BiCMOS
- Silicon scaled and nanoscale devices
- SOI and 3-D Devices
- Spin-based devices
- Superconducting devices
- Thin film transistors
- Tunneling and hot-electron devices
- Wide-bandgap devices

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JUNE 21–23, 2004
UNIVERSITY OF NOTRE DAME, NOTRE DAME, INDIANA

All prospective authors/attendees, please complete and return

- I plan to attend the conference.
- I wish to make a presentation at the conference and have enclosed an abstract.
- Please send me future announcements.

TITLE OF PRESENTATION: _____

AUTHORS NAMES & AFFILIATION: _____

NAME: _____

TITLE: _____

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